



U.S. Army Research, Development and Engineering Command



***TECHNOLOGY DRIVEN. WARFIGHTER FOCUSED.***

# **BLACK SILICON FOR NEXT-GENERATION INFRARED SENSORS**

Dr. Jeffrey Warrender

**August 2012**

Report Documentation Page				Form Approved OMB No. 0704-0188	
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1. REPORT DATE <b>AUG 2012</b>		2. REPORT TYPE		3. DATES COVERED <b>00-00-2012 to 00-00-2012</b>	
4. TITLE AND SUBTITLE <b>Black Silicon for Next-Generation Infrared Sensors</b>				5a. CONTRACT NUMBER	
				5b. GRANT NUMBER	
				5c. PROGRAM ELEMENT NUMBER	
6. AUTHOR(S)				5d. PROJECT NUMBER	
				5e. TASK NUMBER	
				5f. WORK UNIT NUMBER	
7. PERFORMING ORGANIZATION NAME(S) AND ADDRESS(ES) <b>U.S. Army Research, Development and Engineering Command, Picatinny Arsenal, NJ, 07806-5000</b>				8. PERFORMING ORGANIZATION REPORT NUMBER	
9. SPONSORING/MONITORING AGENCY NAME(S) AND ADDRESS(ES)				10. SPONSOR/MONITOR'S ACRONYM(S)	
				11. SPONSOR/MONITOR'S REPORT NUMBER(S)	
12. DISTRIBUTION/AVAILABILITY STATEMENT <b>Approved for public release; distribution unlimited</b>					
13. SUPPLEMENTARY NOTES <b>Presented at the 2nd Multifunctional Materials for Defense Workshop in conjunction with the 2012 Annual Grantees'/Contractors' Meeting for AFOSR Program on Mechanics of Multifunctional Materials &amp; Microsystems Held 30 July - 3 August 2012 in Arlington, VA. Sponsored by AFRL, AFOSR, ARO, NRL, ONR, and ARL.</b>					
14. ABSTRACT					
15. SUBJECT TERMS					
16. SECURITY CLASSIFICATION OF:			17. LIMITATION OF ABSTRACT <b>Same as Report (SAR)</b>	18. NUMBER OF PAGES <b>34</b>	19a. NAME OF RESPONSIBLE PERSON
a. REPORT <b>unclassified</b>	b. ABSTRACT <b>unclassified</b>	c. THIS PAGE <b>unclassified</b>			

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Sionyx, Inc.

Martin Pralle, Jim Carey

## ***DoD applications require Infrared light***



***Precision-guided munitions***



***Situational Awareness***



***Hyperspectral weapon sights***



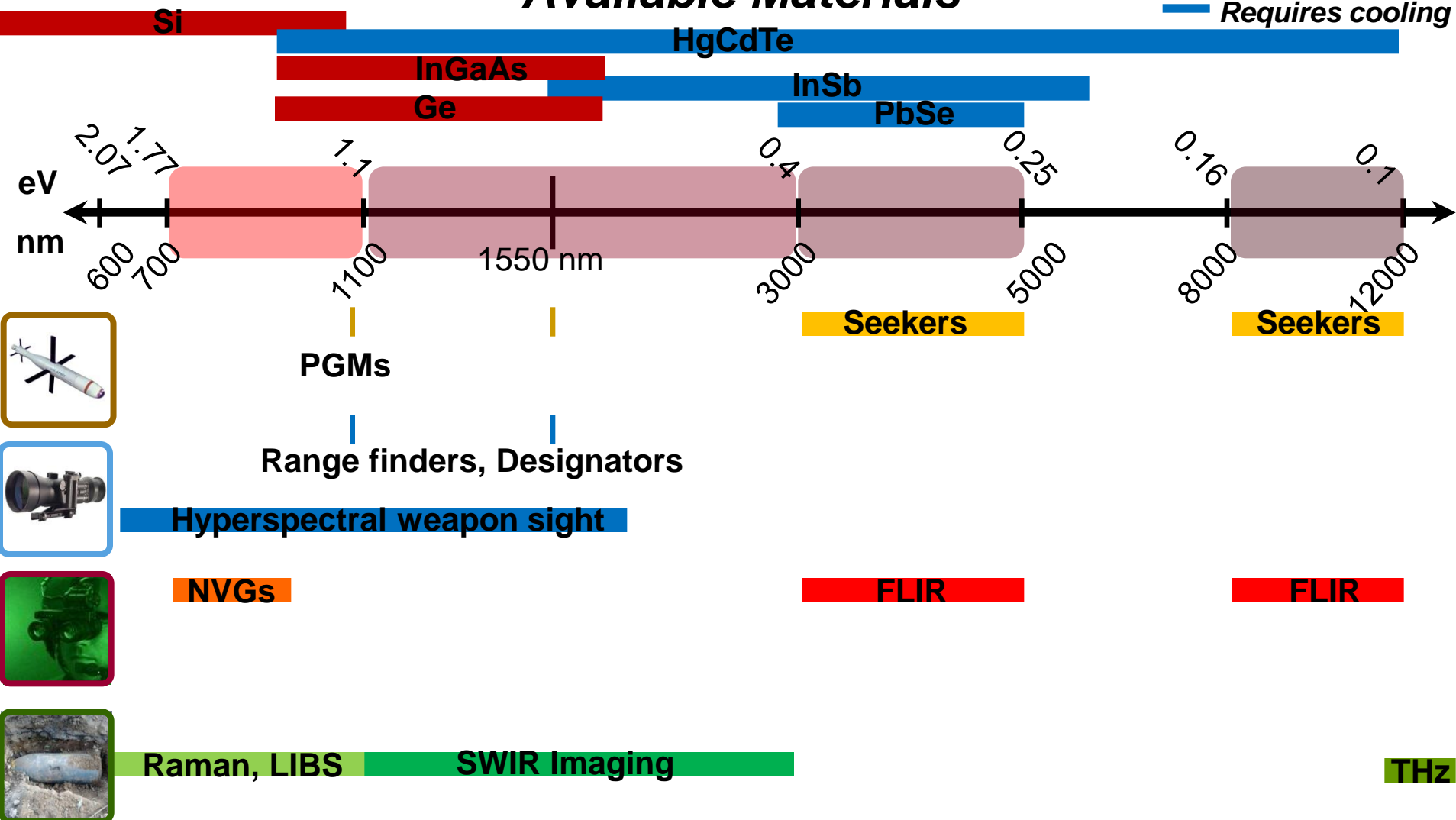
***Photovoltaics***



***Standoff Explosive Detection***

# Available Materials

— RT operation  
— Requires cooling



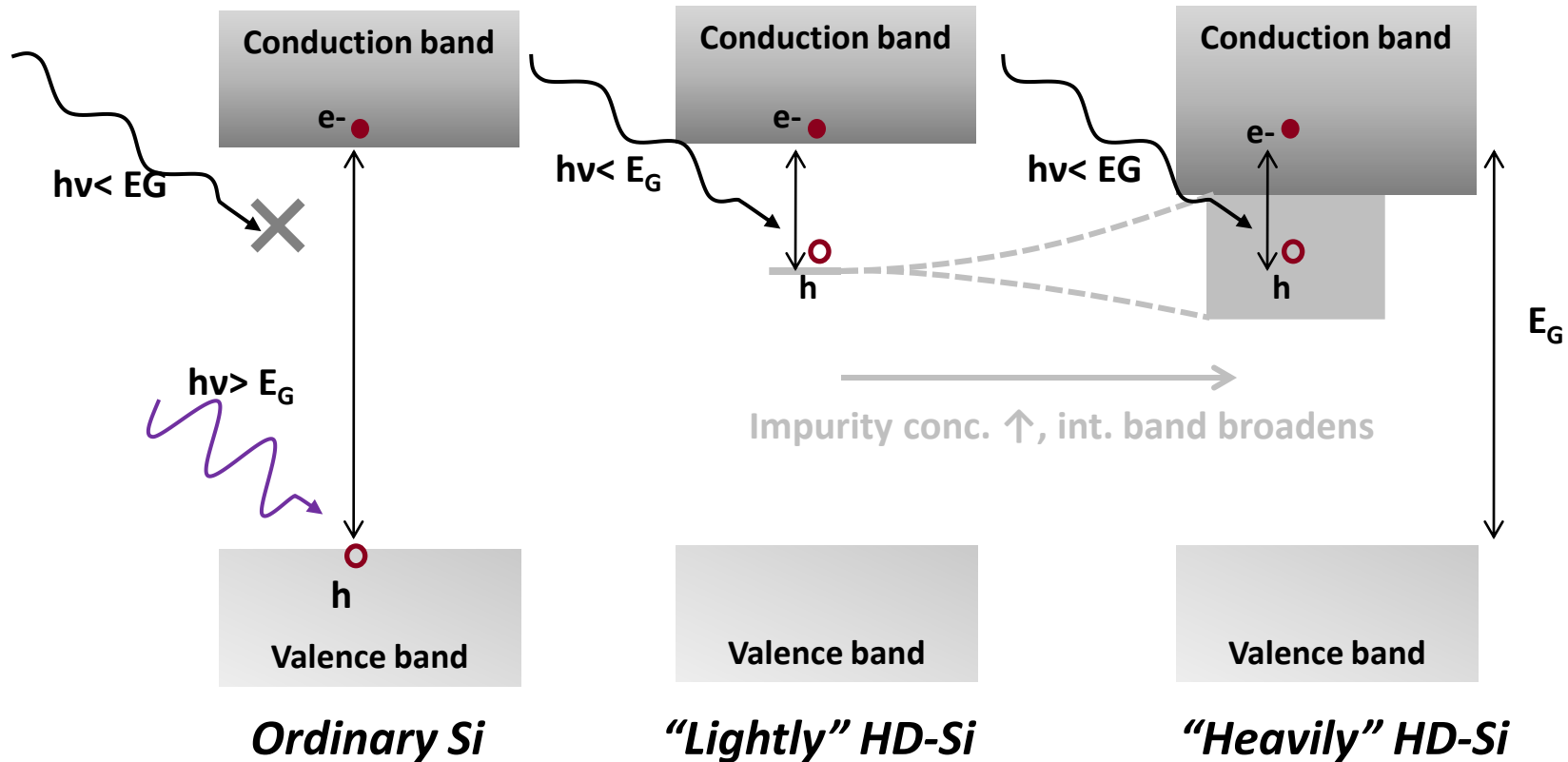
## ***Silicon-based IR optoelectronics***

**Silicon is...**

- +** {
  - Ubiquitous**
  - Inexpensive**
  - Well-characterized**
  - Easy to integrate with readout circuitry**
- {
  - Non-absorbing for wavelengths > 1100 nm**

***Can we dope Si to see IR response?***

## Hyperdoping: Create mid gap states



# Chalcogen dopants in silicon

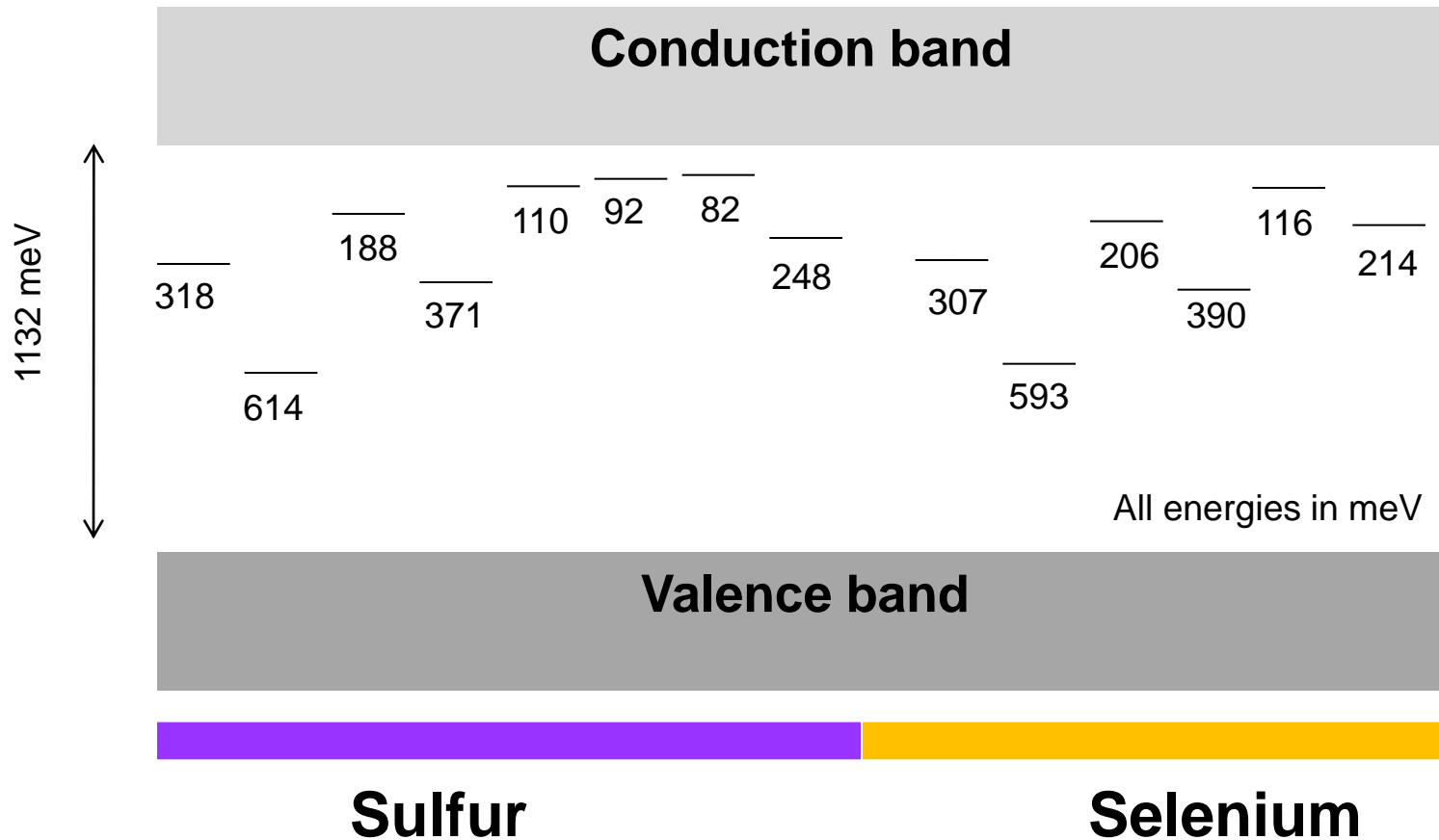
The Periodic Table of the Elements

1 <b>H</b> Hydrogen 1.00794																	2 <b>He</b> Helium 4.003														
3 <b>Li</b> Lithium 6.941	4 <b>Be</b> Beryllium 9.012182											5 <b>B</b> Boron 10.811	6 <b>C</b> Carbon 12.0107	7 <b>N</b> Nitrogen 14.00674	8 <b>O</b> Oxygen 15.9994	9 <b>F</b> Fluorine 18.9984032	10 <b>Ne</b> Neon 20.1797														
11 <b>Na</b> Sodium 22.989770	12 <b>Mg</b> Magnesium 24.3050											13 <b>Al</b> Aluminum 26.981538	14 <b>Si</b> Silicon 28.0855	15 <b>P</b> Phosphorus 30.97376	16 <b>S</b> Sulfur 32.066	17 <b>Cl</b> Chlorine 35.4527	18 <b>Ar</b> Argon 39.948														
19 <b>K</b> Potassium 39.0983	20 <b>Ca</b> Calcium 40.078	21 <b>Sc</b> Scandium 44.955910	22 <b>Ti</b> Titanium 47.867	23 <b>V</b> Vanadium 50.9415	24 <b>Cr</b> Chromium 51.9961	25 <b>Mn</b> Manganese 54.938049	26 <b>Fe</b> Iron 55.845	27 <b>Co</b> Cobalt 58.933200	28 <b>Ni</b> Nickel 58.6934	29 <b>Cu</b> Copper 63.546	30 <b>Zn</b> Zinc 65.39	31 <b>Ga</b> Gallium 69.723	32 <b>Ge</b> Germanium 72.61	33 <b>As</b> Arsenic 74.9216	34 <b>Se</b> Selenium 78.96	35 <b>Br</b> Bromine 79.904	36 <b>Kr</b> Krypton 83.80														
37 <b>Rb</b> Rubidium 85.4678	38 <b>Sr</b> Strontium 87.62	39 <b>Y</b> Yttrium 88.90585	40 <b>Zr</b> Zirconium 91.224	41 <b>Nb</b> Niobium 92.90638	42 <b>Mo</b> Molybdenum 95.94	43 <b>Tc</b> Technetium (98)	44 <b>Ru</b> Ruthenium 101.07	45 <b>Rh</b> Rhodium 102.90550	46 <b>Pd</b> Palladium 106.42	47 <b>Ag</b> Silver 107.8682	48 <b>Cd</b> Cadmium 112.411	49 <b>In</b> Indium 114.818	50 <b>Sn</b> Tin 118.710	51 <b>Sb</b> Antimony 121.760	52 <b>Te</b> Tellurium 127.60	53 <b>I</b> Iodine 126.90447	54 <b>Xe</b> Xenon 131.29														
55 <b>Cs</b> Cesium 132.90545	56 <b>Ba</b> Barium 137.327	57 <b>La</b> Lanthanum 138.9055	72 <b>Hf</b> Hafnium 178.49	73 <b>Ta</b> Tantalum 180.9479	74 <b>W</b> Tungsten 183.84	75 <b>Re</b> Rhenium 186.207	76 <b>Os</b> Osmium 190.23	77 <b>Ir</b> Iridium 192.217	78 <b>Pt</b> Platinum 195.078	79 <b>Au</b> Gold 196.96655	80 <b>Hg</b> Mercury 200.59	81 <b>Tl</b> Thallium 204.3833	82 <b>Pb</b> Lead 207.2	83 <b>Bi</b> Bismuth 208.98038	84 <b>Po</b> Polonium (209)	85 <b>At</b> Astatine (210)	86 <b>Rn</b> Radon (222)														
87 <b>Fr</b> Francium (223)	88 <b>Ra</b> Radium (226)	89 <b>Ac</b> Actinium (227)	104 <b>Rf</b> Rutherfordium (261)	105 <b>Db</b> Dubnium (262)	106 <b>Sg</b> Seaborgium (263)	107 <b>Bh</b> Bohrium (262)	108 <b>Hs</b> Hassium (265)	109 <b>Mt</b> Meitnerium (266)	110  (269)	111  (272)	112  (277)	113  	114  																		
																		58 <b>Ce</b> Cerium 140.116	59 <b>Pr</b> Praseodymium 140.90765	60 <b>Nd</b> Neodymium 144.24	61 <b>Pm</b> Promethium (145)	62 <b>Sm</b> Samarium 150.36	63 <b>Eu</b> Europium 151.964	64 <b>Gd</b> Gadolinium 157.25	65 <b>Tb</b> Terbium 158.92534	66 <b>Dy</b> Dysprosium 162.50	67 <b>Ho</b> Holmium 164.93032	68 <b>Er</b> Erbium 167.26	69 <b>Tm</b> Thulium 168.93421	70 <b>Yb</b> Ytterbium 173.04	71 <b>Lu</b> Lutetium 174.967
																		90 <b>Th</b> Thorium 232.0381	91 <b>Pa</b> Protactinium 231.03588	92 <b>U</b> Uranium 238.0289	93 <b>Np</b> Neptunium (237)	94 <b>Pu</b> Plutonium (244)	95 <b>Am</b> Americium (243)	96 <b>Cm</b> Curium (247)	97 <b>Bk</b> Berkelium (247)	98 <b>Cf</b> Californium (251)	99 <b>Es</b> Einsteinium (252)	100 <b>Fm</b> Fermium (257)	101 <b>Md</b> Mendelevium (258)	102 <b>No</b> Nobelium (259)	103 <b>Lr</b> Lawrencium (262)



## Chalcogen dopants in silicon

Binding energies of chalcogen centers in Si



Janzen et al., *Phys Rev B* (1984)

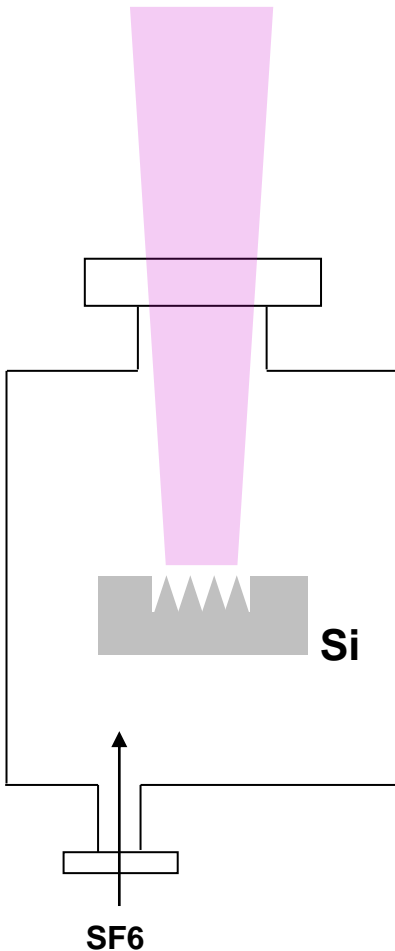
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# Spiked Black Silicon

Harvard (Mazur)/ Sionyx



Pulsed laser



Crouch et al, *Appl Phys Lett* (2004)

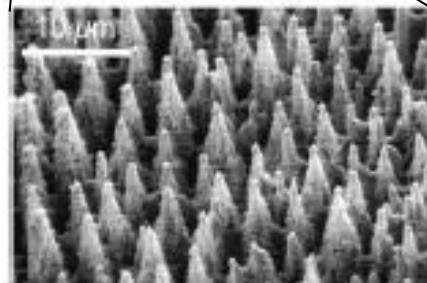
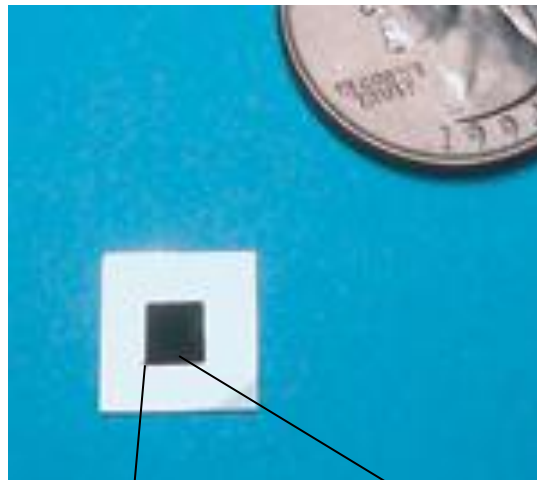
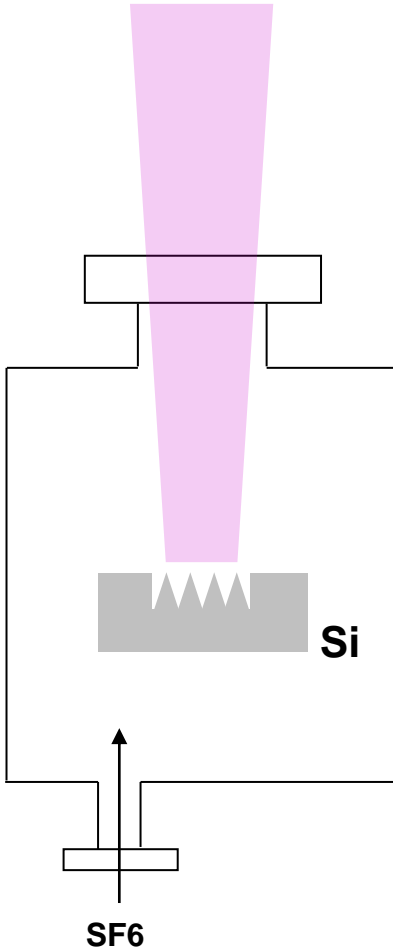
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# Spiked Black Silicon

Harvard (Mazur)/ Sionyx



Pulsed laser



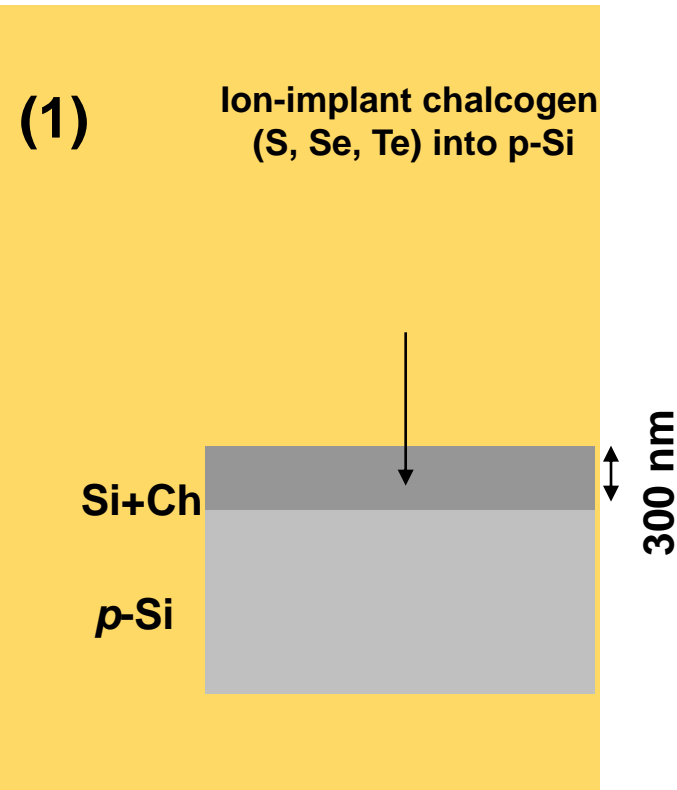
Crouch et al, *Appl Phys Lett* (2004)

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## Flat Black Silicon

Harvard (Aziz)/ ARDEC



Kim *et al*, *Appl Phys Lett* (2006)  
Tabbal *et al*, *JVST B* (2007)

Bob *et al*, submitted to *J Appl Phys*

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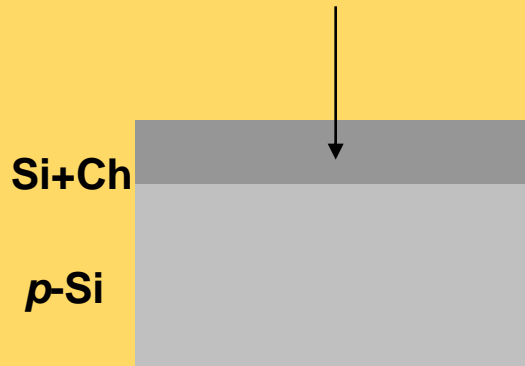


## Flat Black Silicon

Harvard (Aziz)/ ARDEC

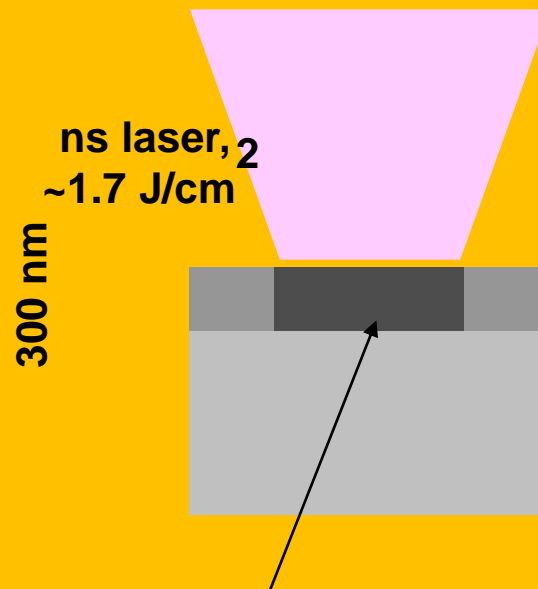
(1)

Ion-implant chalcogen  
(S, Se, Te) into p-Si



(2)

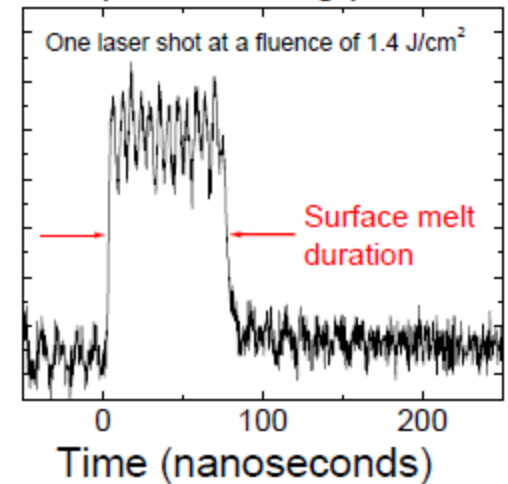
Pulsed-laser melting (PLM)  
“heals” implant damage



Crystalline Si,  
supersaturated in Ch, *n*-  
type

Reflectivity Signal

Temporal melting profile of Si



Kim *et al*, *Appl Phys Lett* (2006)  
Tabbal *et al*, *JVST B* (2007)

Bob *et al*, *JAP* (2010)

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## Benet Labs' Black Silicon setup

Nd:YAG laser  
1064/532/355/266 nm  
4 ns pulse duration



$\lambda/2$  plate

Ar ion laser (CW)  
488 nm  
1.2 W



Lenses

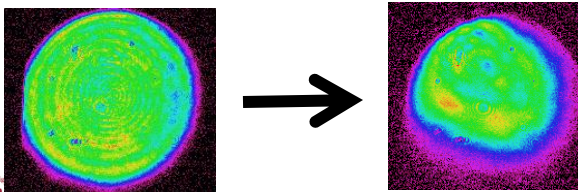
Motorized stage

Fast photodiode

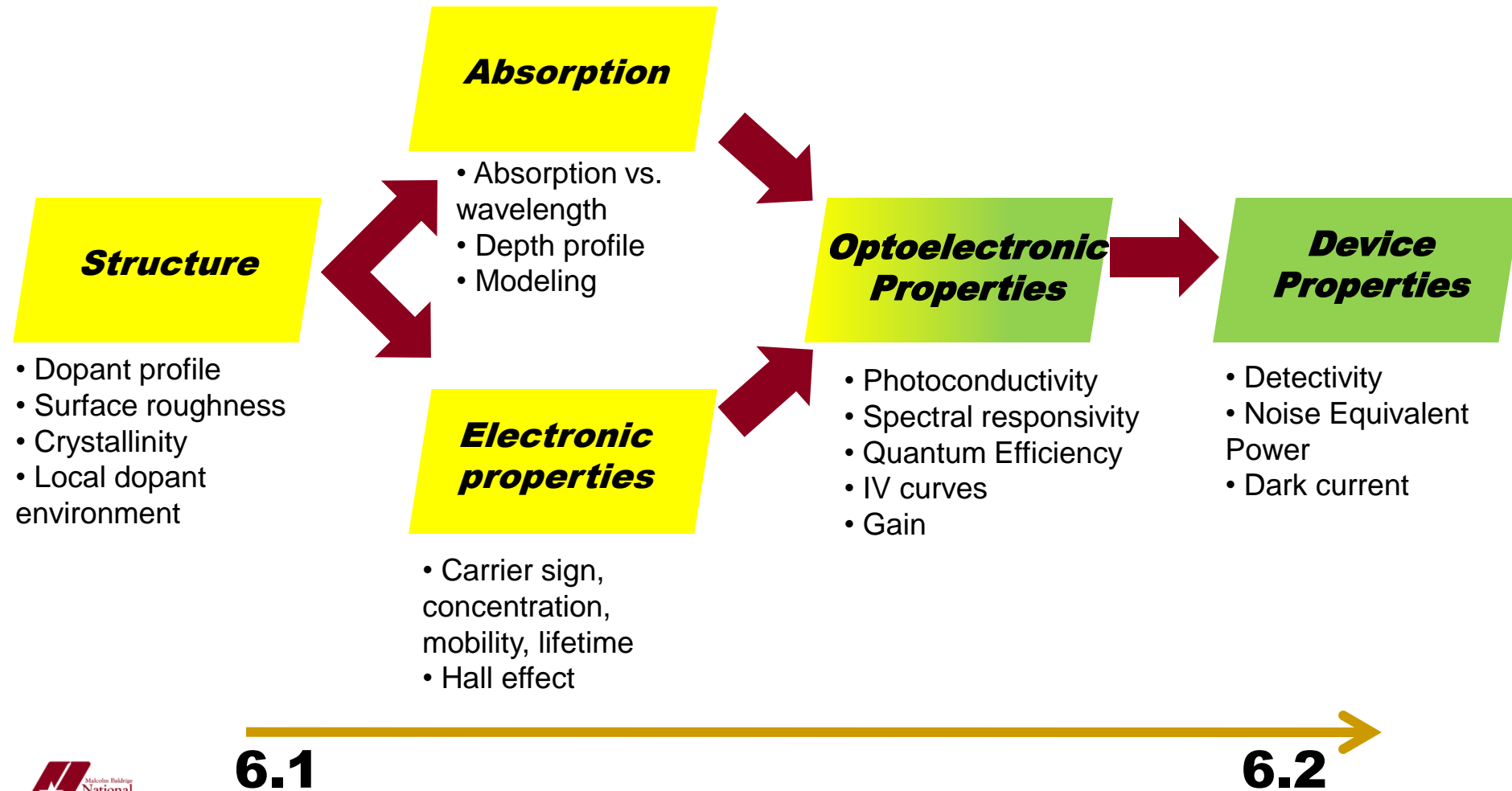
Vacuum chamber

Oscilloscope

Relay-image w/pinhole

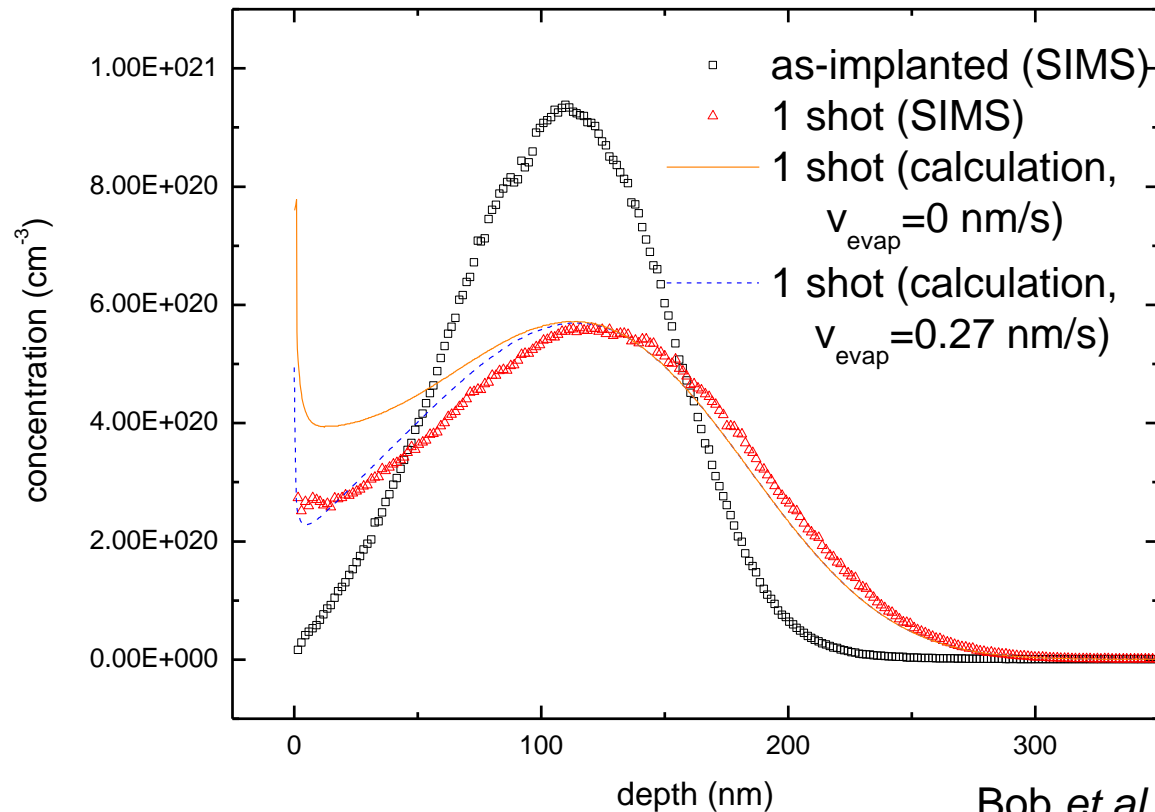


## Characterization Logical Flow



**Structure**

# Dopant depth profile evolution

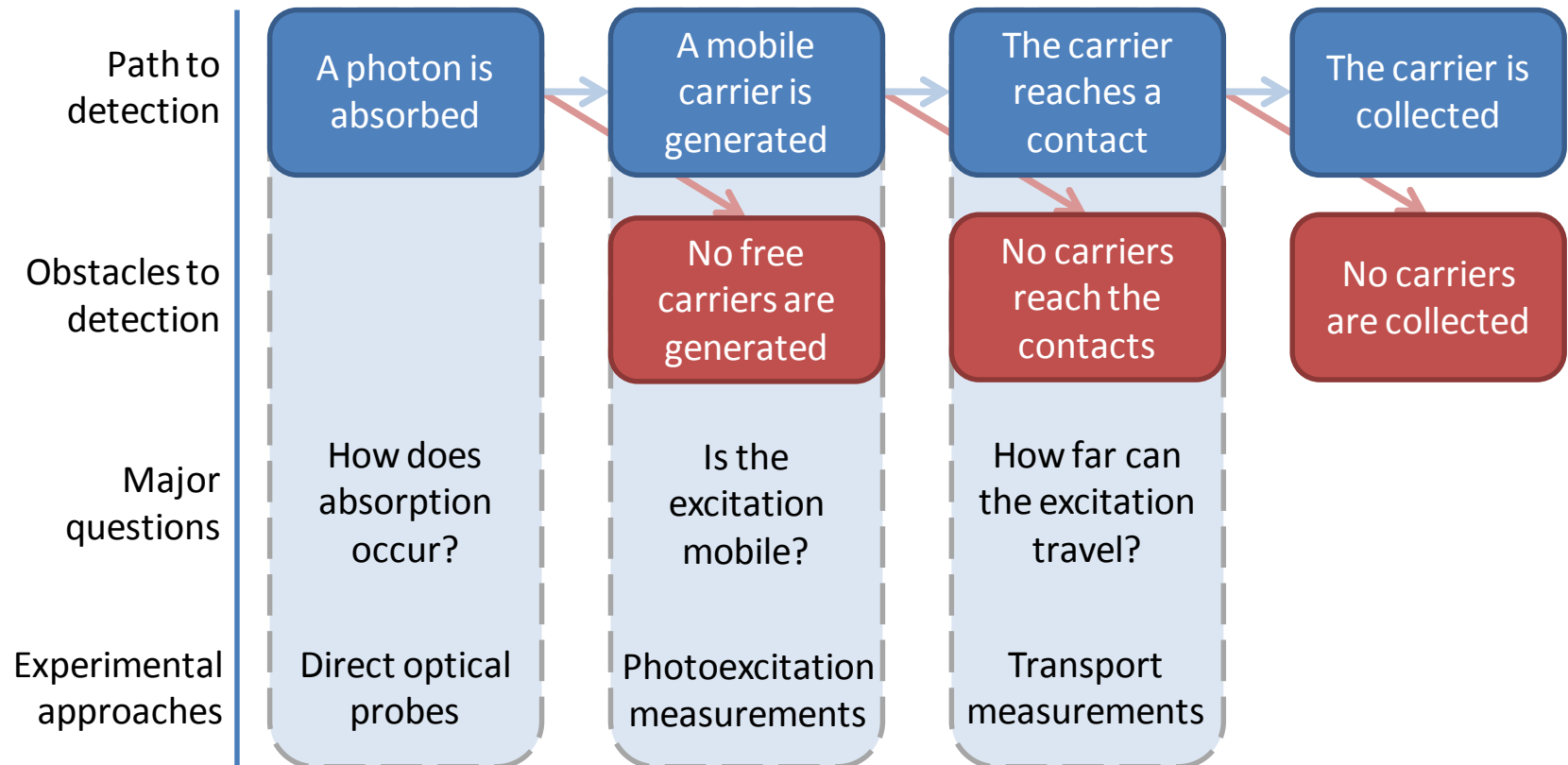


Bob et al, JAP (2010)

BUT, as laser shots  $\uparrow$ ,  $v_{\text{evap}} \downarrow$



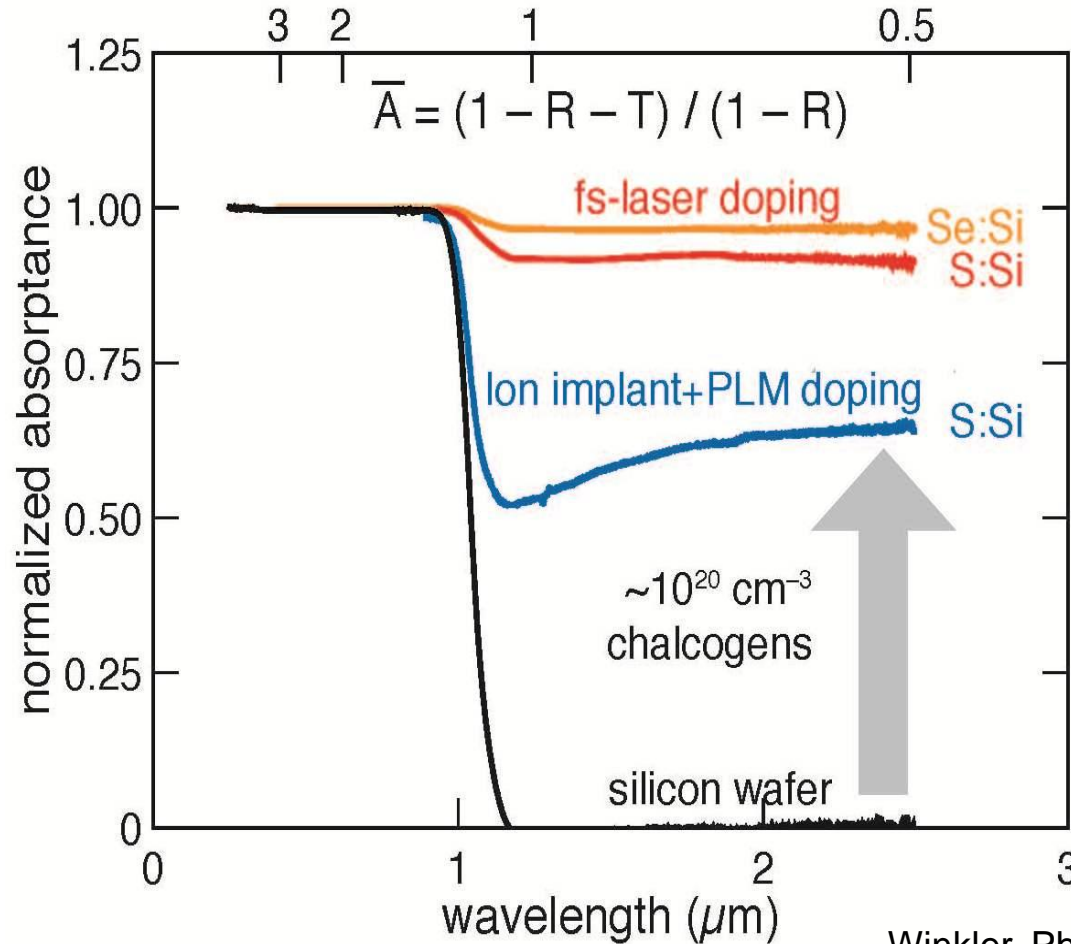
## Our approach to studying hyperdoped silicon



# Absorption

photon energy (eV)

**Absorption**

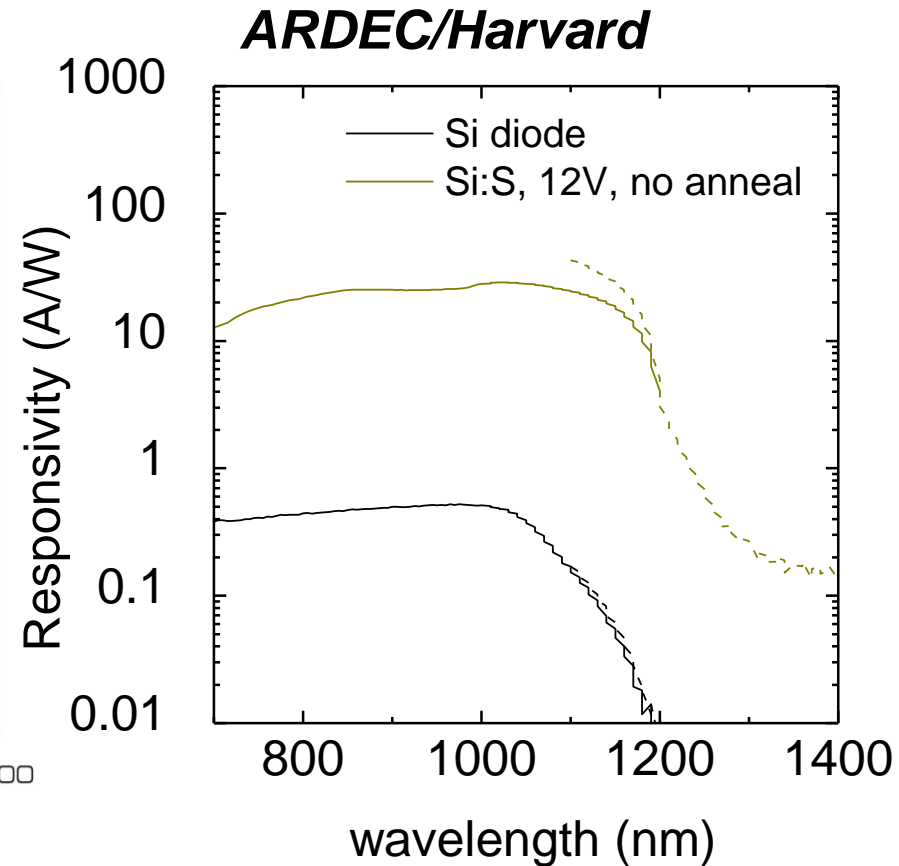
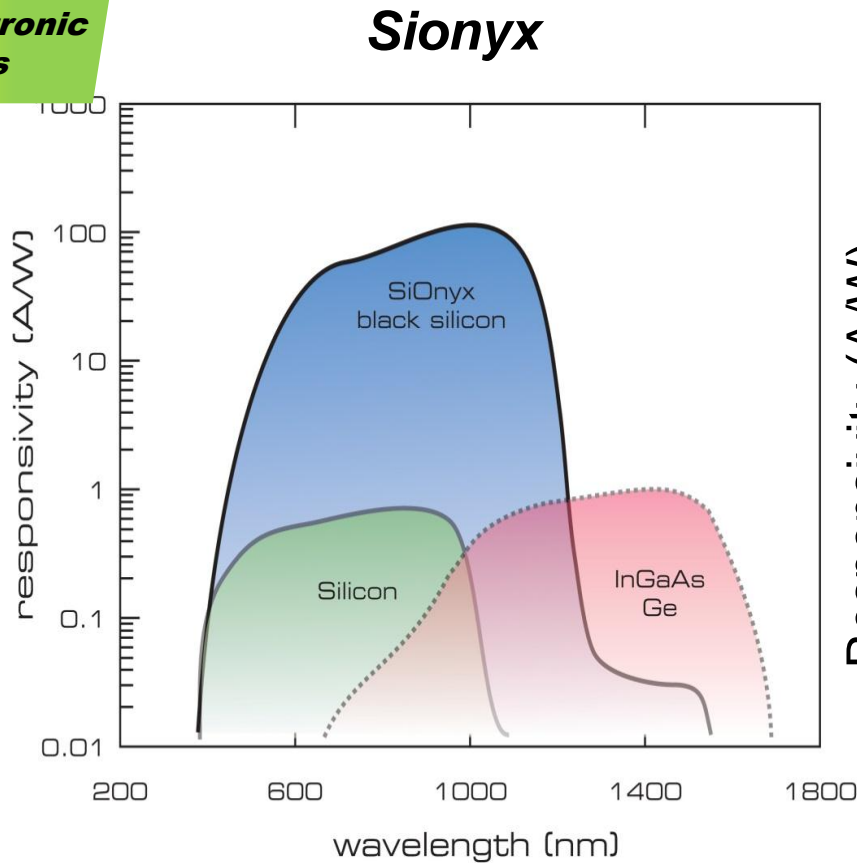


Winkler, Ph.D. thesis, Harvard (2010)

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## Responsivity comparison

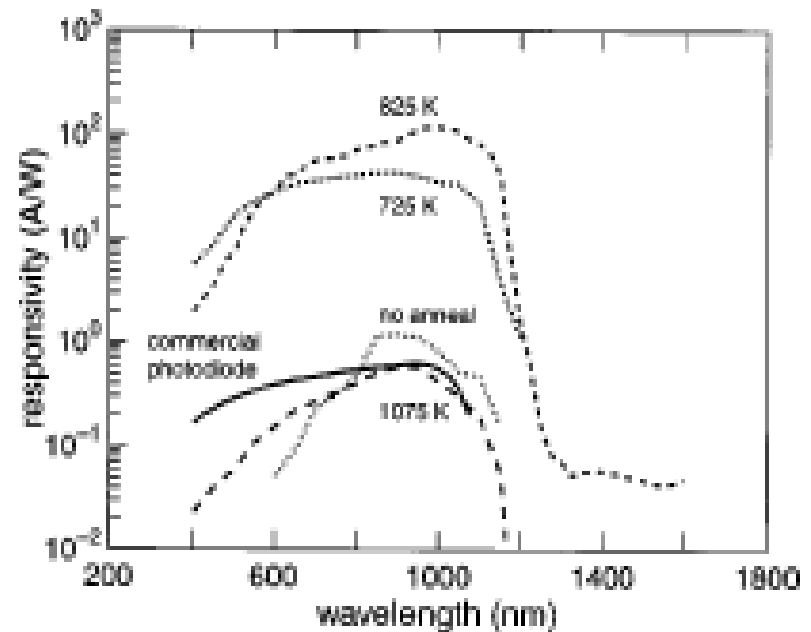
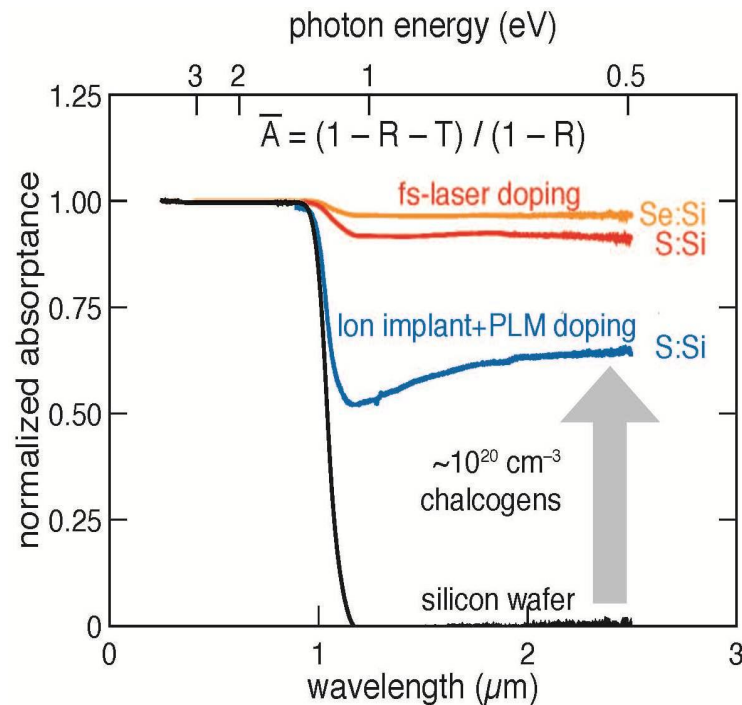
**Optoelectronic Properties**



Said et al, *APL* (2011)

**TECHNOLOGY DRIVEN. WARFIGHTER FOCUSED.**

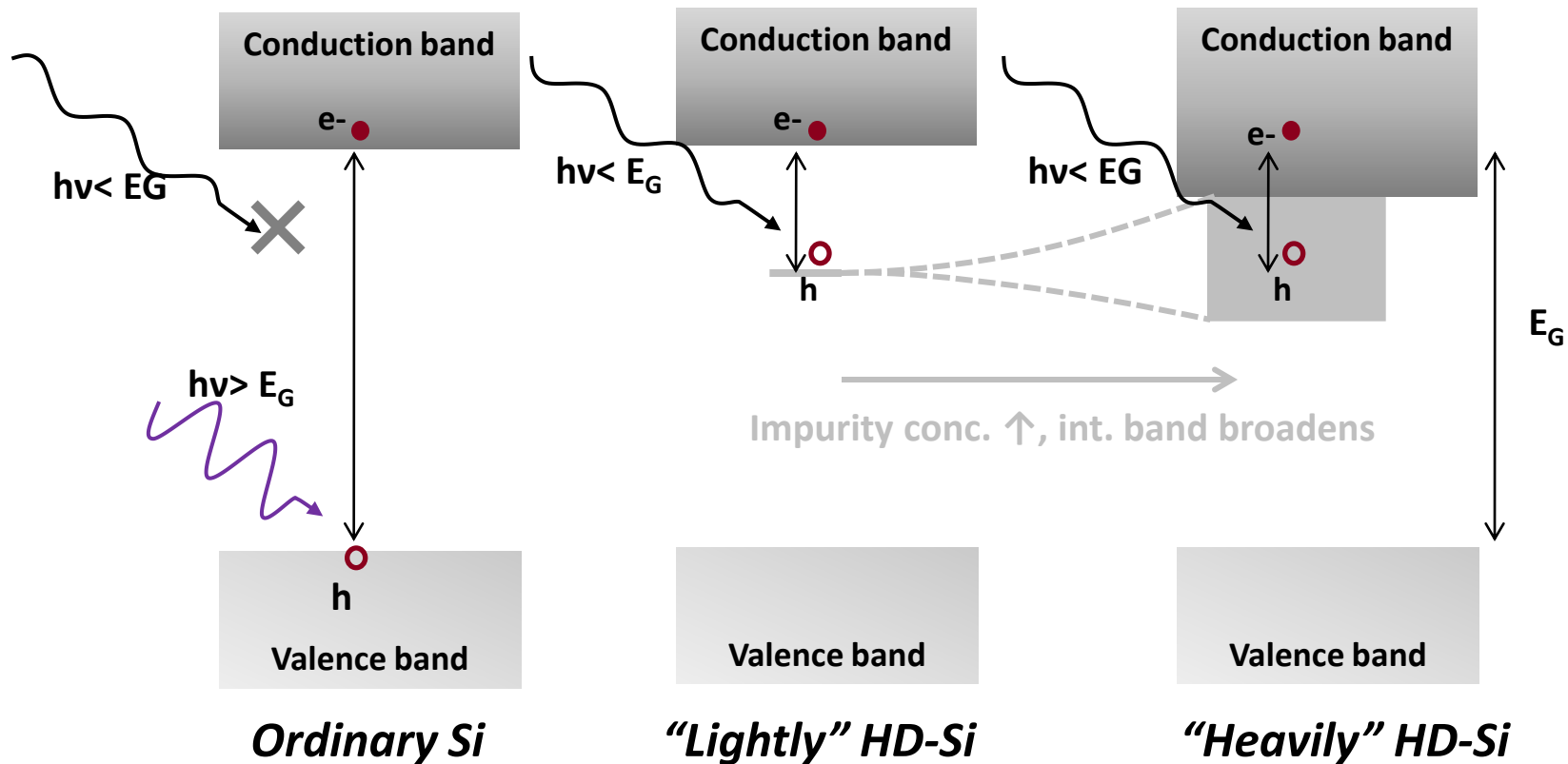
## An apparent conundrum



Strong, broadband absorption...

...but no device response

## Possible reconciliation



## Other Strategies to Try

*Less dopant*

*Change dopant*

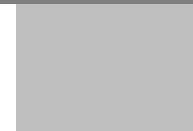
*Add dopant*

Conduction band

Conduction band

Conduction band

Conduction band



Valence band

Valence band

Valence band

Valence band

Move states out of  
conduction band

Move states  
deeper into band  
gap






Compensate  
impurity band  
gap

# The Larger Black Silicon Universe










## Stakeholders

Extended  
IR needed?  
Existing  
BSi ok?

System

	<b>CERDEC-NVESD</b>	Digital Nightvision	X	
	<b>USMC</b>	CLRF	X	X
	<b>ONR</b>	DETECT, CLRF	X	X
	<b>White Sands Missile Range</b>	Airborne Laser	X	
	<b>ARDEC</b>	Precision-guided	X	X

## Research Groups

	<b>Harvard</b> Aziz
	<b>ARDEC-Benet</b> Warrender
	<b>RPI</b> Persans
	<b>MIT</b> Buonassisi
	<b>Harvard</b> Mazur
	<b>MIT</b> Gradecak
	<b>MIT</b> Grossman
	<b>Illinois</b> Ertekin
	<b>Sionyx</b> Pralle, Carey

Extended IR response,  
optoelectronic  
charazterization

Characterization of fs-  
structured Black Silicon

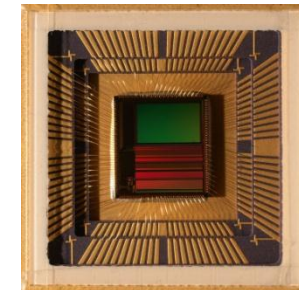
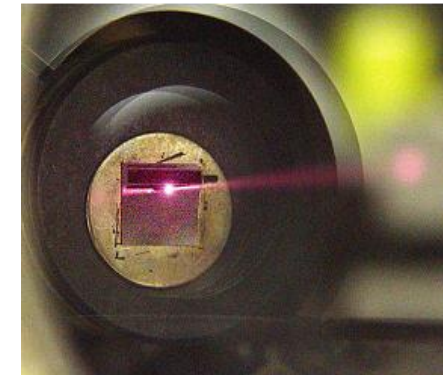
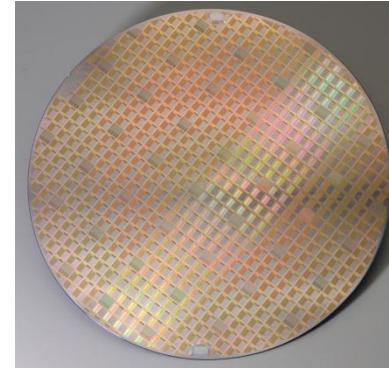
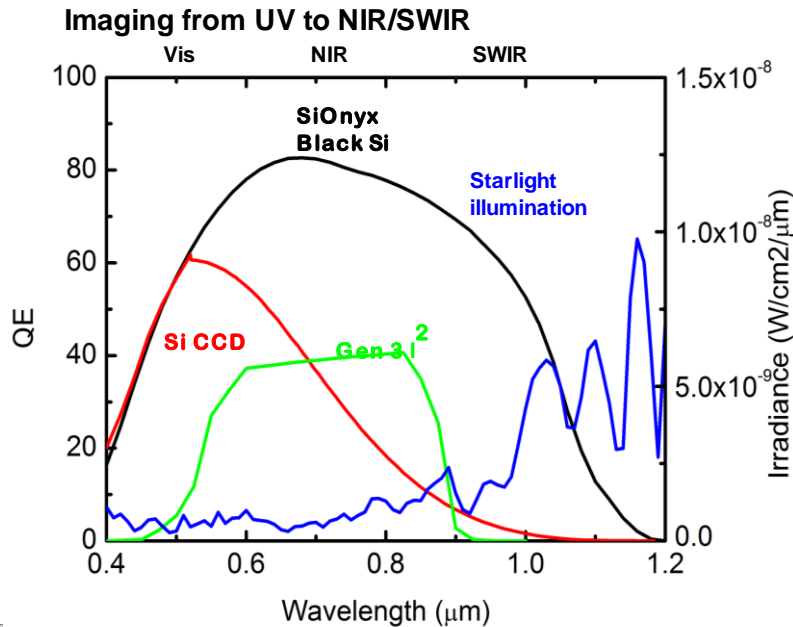
First principles modeling

Commercialization

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# SiOnyx IR CMOS: Black Silicon enhanced imaging



- Low cost 8" CMOS manufacturing
- Low Noise (Read noise ~2 e/pix)  
(Dark Current <8e/pix/frame)
- Low Power (300 mW @ 800x600)
- Compact Size
- TRL 6 imaging device
- TRL 6 wafer process



[mupralle@sionyx.com](mailto:mupralle@sionyx.com), 978-922-0684x127

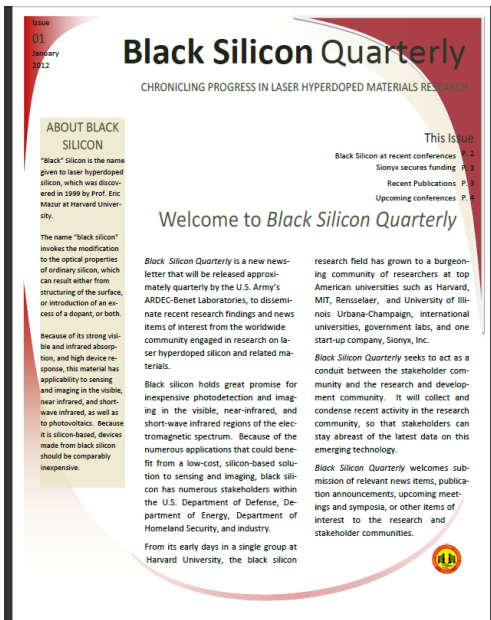
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# Outreach

## Black Silicon Quarterly

- News and recent black silicon goings-on
- Send an email to [jeffrey.m.warrender.civ@mail.mil](mailto:jeffrey.m.warrender.civ@mail.mil) to be added to distribution



## Black Silicon Symposium

- Held in Albany, NY
- August 9-10



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## ***Summary and Outlook***

- **Laser hyperdoped “black” silicon can be made by two different approaches**
  - Similar properties
  - “Flat” black silicon easier to study
- **Strong sub band gap absorption**
- **High EQE out to 1200 nm**
- **ARDEC seeks to extend strong device response to 1700 nm**
- **Fundamental and practical questions abound**

**[jeffrey.m.warrender.civ@mail.mil](mailto:jeffrey.m.warrender.civ@mail.mil)**

# ***BACKUP SLIDES***

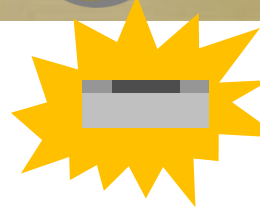
## ***Research interests at Benet***

- Extending black silicon's IR response
- Characterizing the properties of ns-spiked black Si
- Exploring broader slice of parameter space
  - Non-chalcogen dopants, thick layers, 5 ns pulses, non-UV wavelengths
- Increasing process cleanliness
- Black Si photovoltaics

## Assets



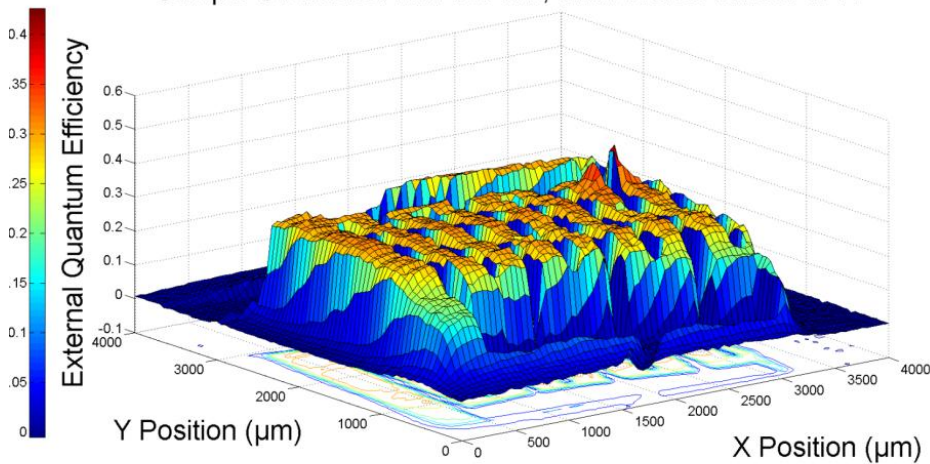
Laser/tool	Purpose	Capabilities
Ekspla NL313	Laser melting	532 nm/ 355 nm 800/500 mJ output 5 ns pulse duration
Coherent I-306	Surface reflectivity	514/488/458 nm 2.4/1.8/0.42 W output CW
Resonetics Excimer system	Laser melting	248 nm 400 mJ output 20 ns pulse duration
Vacuum chamber with motorized stage	Wafer-scale clean processing	150 mm Si wafer processing
Dual-beam FE-SEM/FIB	TEM sample prep, High-res imaging	System spec pending



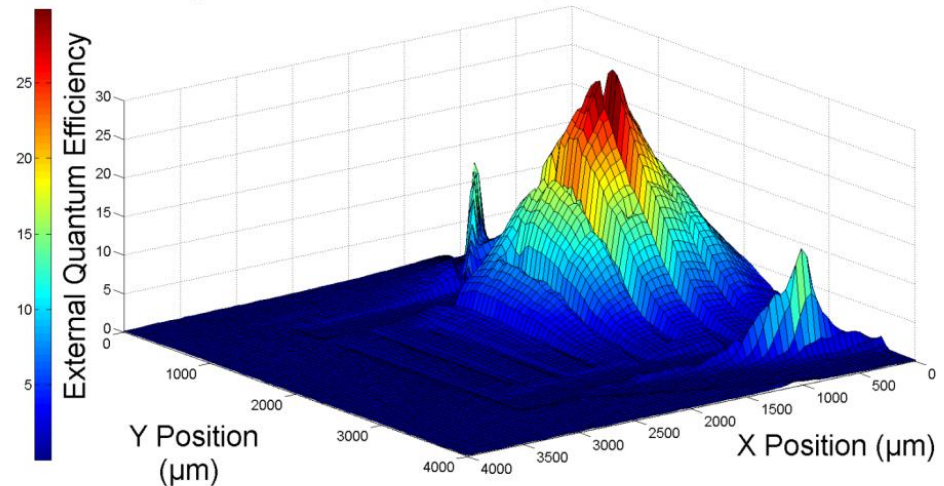
# *Gain is spatially inhomogeneous*

## **Optoelectronic Properties**

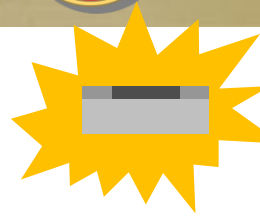
Sample U rastered with 650 nm, and reverse biased at 1V



Sample U rastered with 980 nm, and reverse biased at 12V



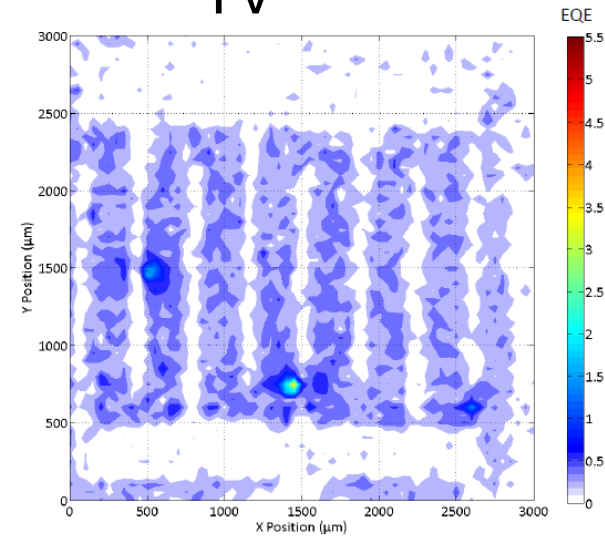




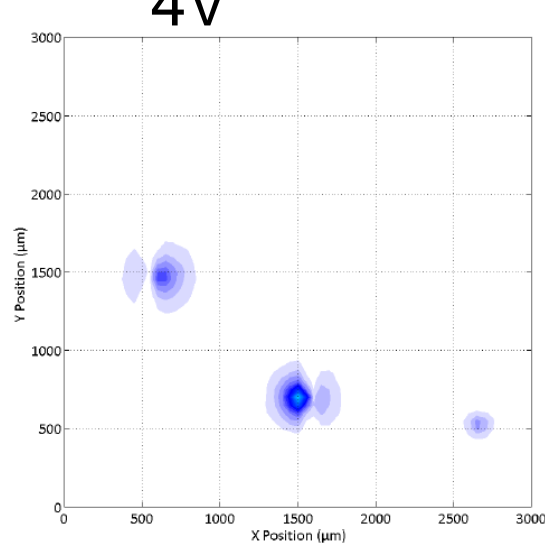
**Optoelectronic  
Properties**

# Gain is spatially inhomogeneous

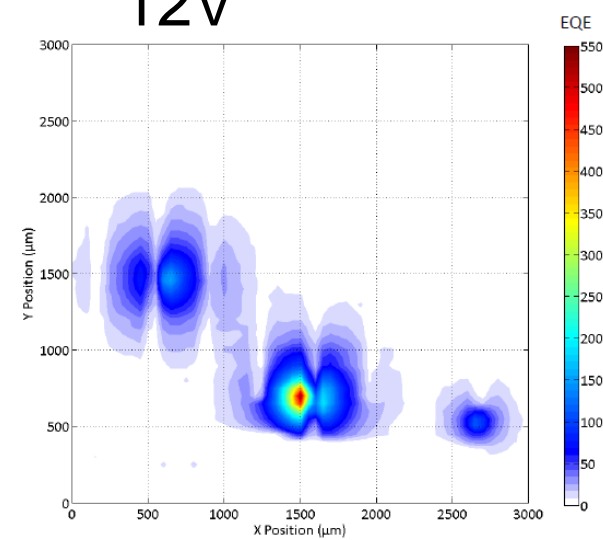
1V



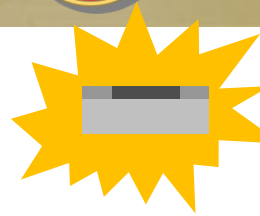
4V



12V



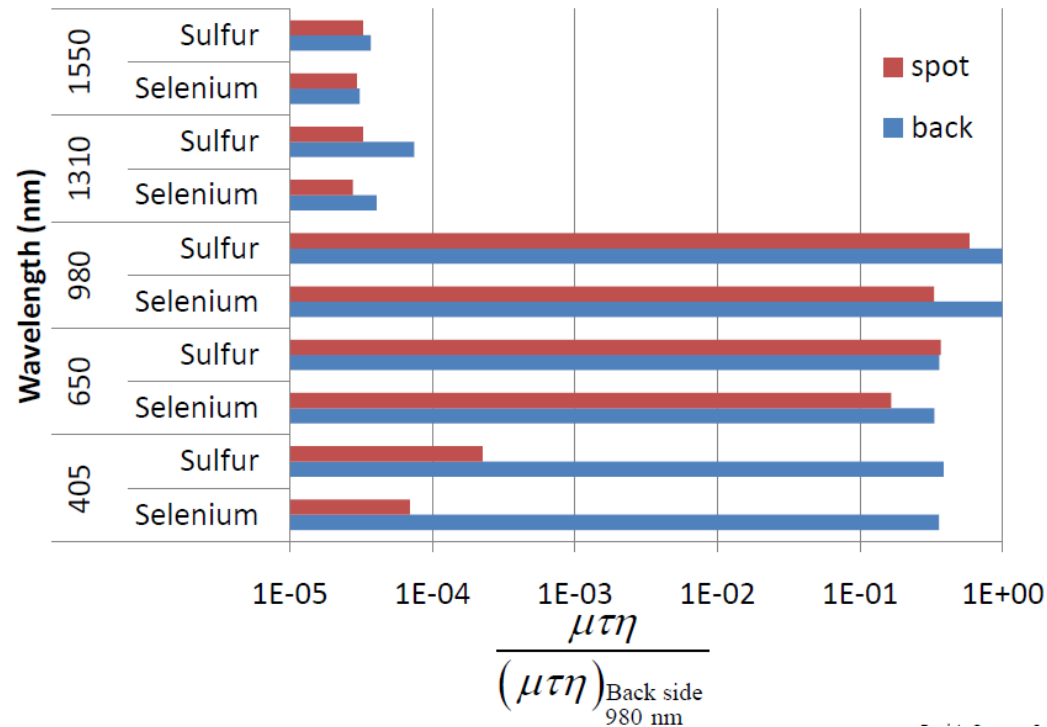
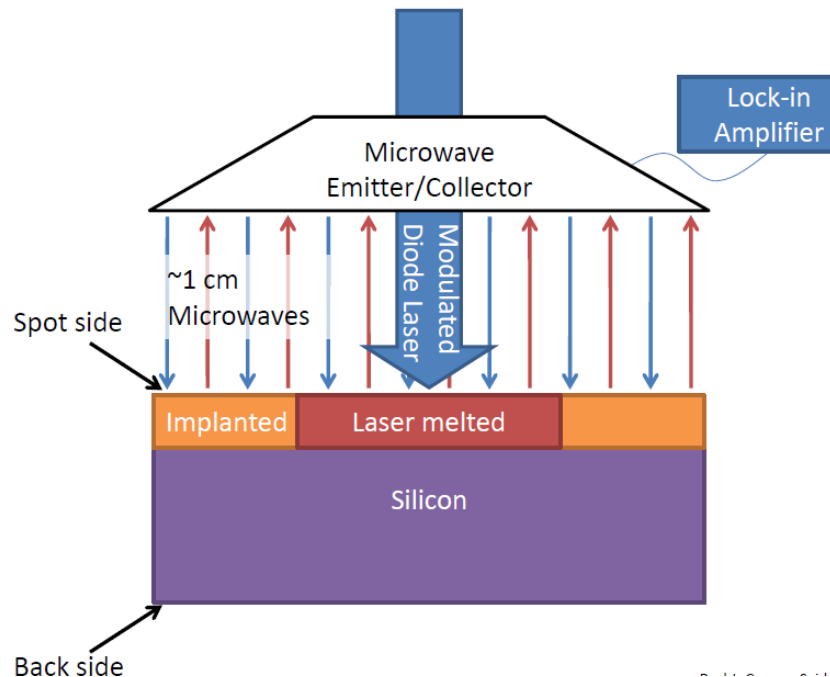
1e15/cm<sup>2</sup> S in Si, 4 laser shots, Ti/Ni/Ag contacts, 980 nm probe laser, reverse bias



*...but the story gets even weirder*

**Optoelectronic Properties**

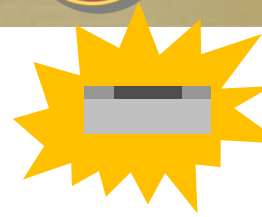
Microwave reflectivity



*No detectable photoconductivity in the Si:S layer!*

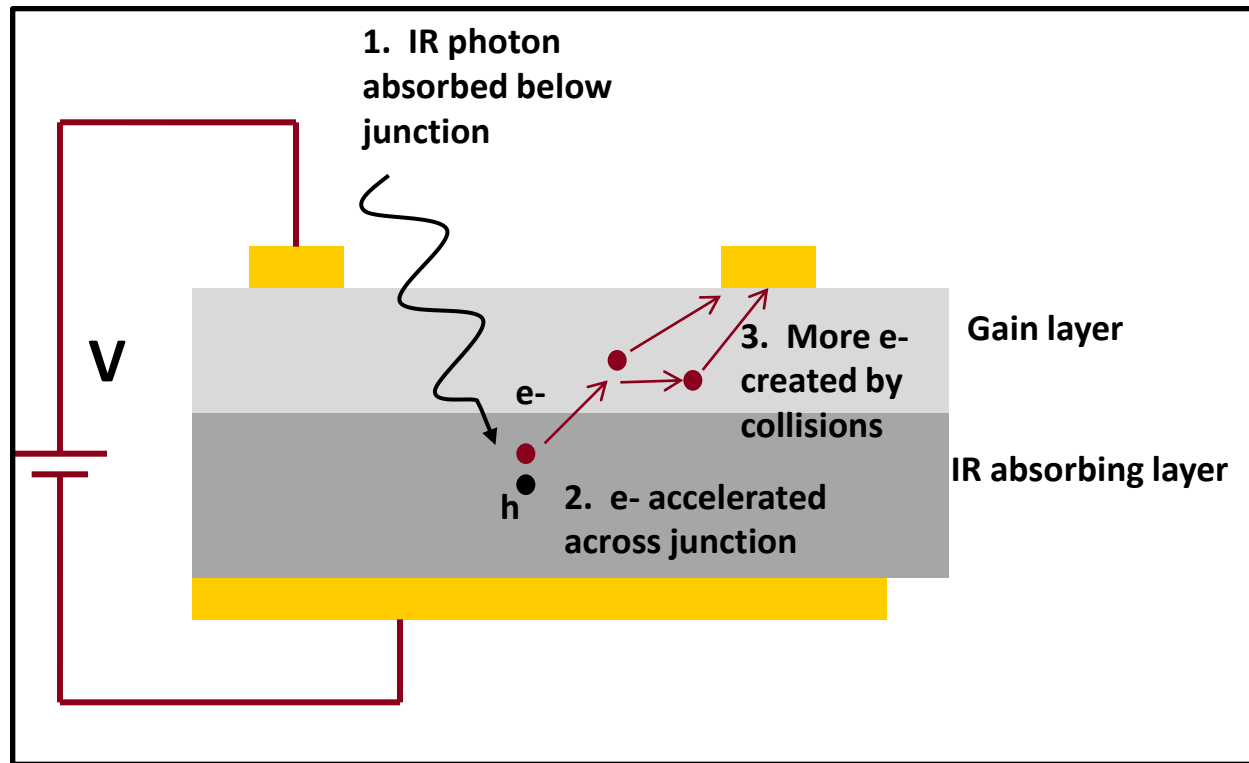
**TECHNOLOGY DRIVEN. WARFIGHTER FOCUSED.**



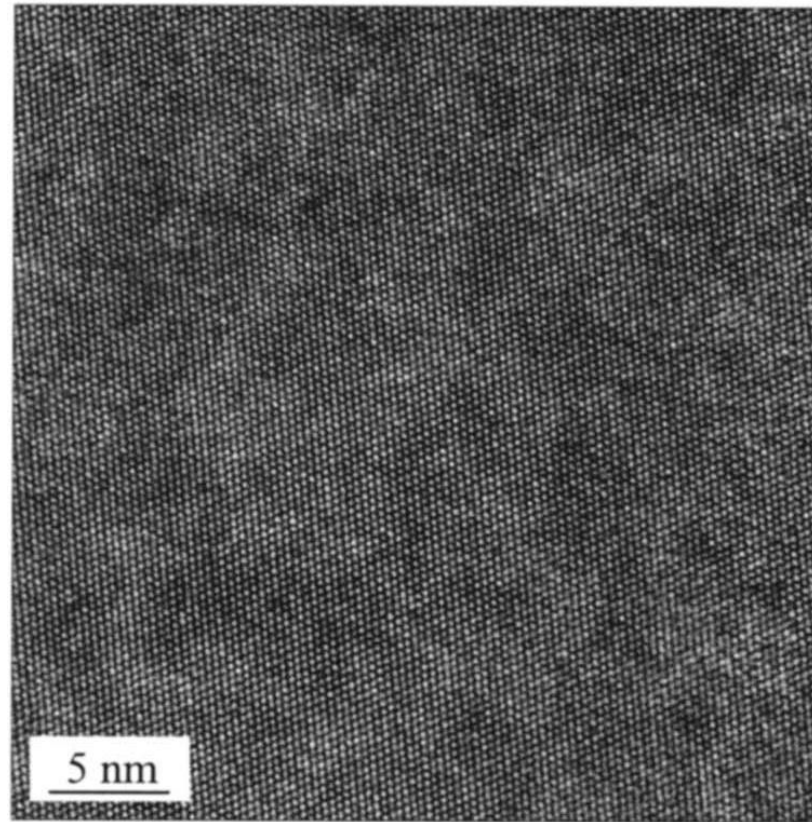


## Gain without photoconductivity?

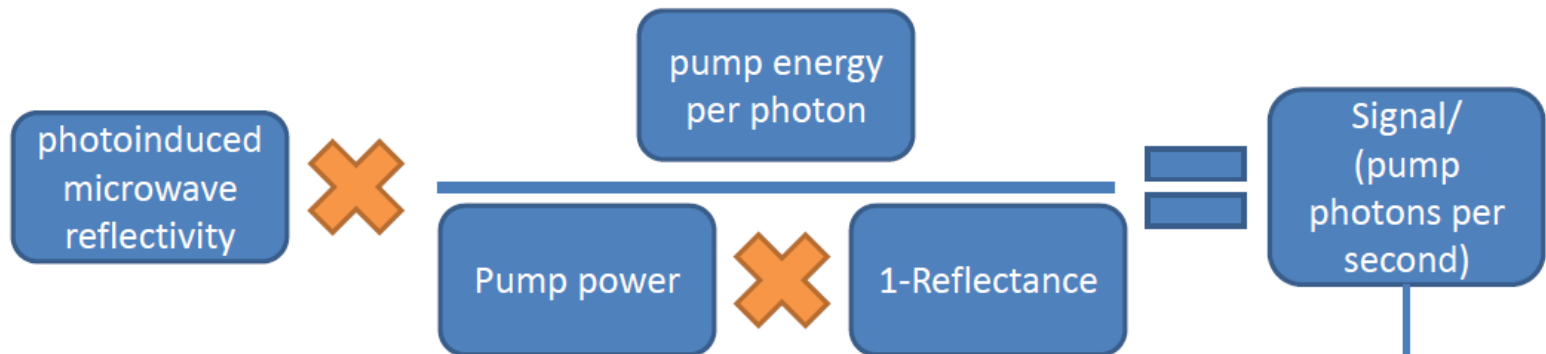
**Optoelectronic  
Properties**



## ***XTEM lattice image of PLM'd material***



# Data were converted to signal per (pump photons per second)



$$\frac{C\Delta\sigma}{\text{photons / sec}} = \frac{Ce\mu\Delta n}{\text{photons / sec}} = \frac{Ce\mu\tau g}{\text{photons / sec}} = \frac{(Ce\mu\tau) \times (\text{photons / sec}) \times (\eta)}{\text{photons / sec}} = Ce\mu\tau\eta$$

Constant dependent on apparatus not sample or pump

Taking the ratio of two measurements removes the influence of the experimental apparatus (C cancels out)